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1. Name of conveying party(ies): Hiroyuki Shimada Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No	2. Name and address of receiving party(ies) Name: <u>Seiko Epson Corporation</u> Internal Address: _____ Street Address: <u>4-1, Nishi-Shinjuku</u> <u>2-chome</u> <u>Shinjuku-ku</u> <u>Tokyo</u> <u>JAPAN</u> City: _____ State: _____ Country: _____ Zip: _____ Additional name(s) & address(es) attached? ☐ Yes ☒ No
3. Nature of conveyance/Execution Date(s): Execution Date(s): <u>March 10, 2006</u> ☒ Assignment ☐ Merger ☐ Change of Name ☐ Security Agreement ☐ Joint Research Agreement ☐ Government Interest Assignment ☐ Executive Order 9424, Confirmatory License ☐ Other _____	4. Application or patent number(s): ☐ This document is being filed together with a new application. A. Patent Application No.(s) <u>11/374,351</u> B. Patent No.(s) _____ Additional numbers attached? ☐ Yes ☒ No
5. Name and address to whom correspondence concerning document should be mailed: Name: <u>John J. Penny, Jr.</u> <u>EDWARDS ANGELL PALMER & DODGE</u> <u>LLP</u> Internal Address: <u>Atty. Dkt.: 64709(48229)</u> Street Address: <u>P.O. Box 55874</u> City: <u>Boston</u> State: <u>MA</u> Zip: <u>02205</u> Phone Number: <u>(617) 439-4444</u> Fax Number: <u>(617) 439-4170</u> Email Address: <u>JPenny@eapdlaw.com</u>	6. Total number of applications and patents involved: 1 7. Total fee (37 CFR 1.21(h) & 3.41) \$ <u>40.00</u> ☐ Authorized to be charged by credit card ☒ Authorized to be charged to deposit account ☐ Enclosed ☐ None required (government interest not affecting title)
8. Payment Information a. Credit Card Last 4 Numbers _____ Expiration Date _____ b. Deposit Account Number <u>04-1105</u> Authorized User Name <u>John J. Penny, Jr.</u>	
9. Signature: _____ Signature <u>George N. Chaclos - 46,608</u> Name of Person Signing <u>April 19, 2006</u> Date Total number of pages including cover sheet, attachments, and documents: 5	

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Seiko Epson Ref. No.: J0115951US01

譲渡証 (Translation/日本語訳)

下記に署名した私/私達、

島田 清行 は、

ある発明を創出し、これについて合衆国特許出願は

- ☒ ここに私/私達により署名され、
☐ _____ に私/私達により (それぞれ) 署名され、
☐ _____ に出願され、出願番号 _____ が交付され、
☐ PCT 国際出願 _____ として _____ に出願され、

その発明は

半導体装置の製造方法及び半導体装置

という名称である。そして、ここにその受領を認める対価で：私/私達は、当該発明/出願について、合衆国とその属領及び全ての外国に於ける全面的かつ排他的な権利；合衆国とその属領及び全ての外国に於いて発行される特許証に関わる全Cの権利、所有権、利益；一部継続出願、継続出願、分割出願、差替え出願、再発行出願、特許期間延長等、合衆国とその属領及び全ての外国に於いて既に出願されたか若しくは今後出願される特許に関わる全ての権利；そして、国際条約、同盟、契約、法令、協定（将来制定されるものを含む）に基づく全ての優先権を伴う一切の権利；を、日本国東京都新宿区西新宿2丁目4番1号に住所を有するセイコーエプソン株式会社、その後継者、譲受人及び法定代理人に対して、完全、排他、移転するものとする。

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Assignment

For good and valuable consideration, the receipt of which is hereby acknowledged, I/WE, the undersigned,

Hiroyuki SHIMADA,

who have created a certain invention for which an application for United States Letters Patent

- ☒ executed by ME/US on even date herewith,
☐ executed by ME/US on _____, (respectively),
☐ filed on _____ and assigned Serial No. _____,
☐ filed as International Application No. _____ filed on _____

and entitled:

METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE

AND SEMICONDUCTOR DEVICE

Do hereby sell, assign and transfer to Seiko Epson Corporation, a corporation of Japan, having a place of business at 4-1, Nishi-shinjuku 2-chome, Shinjuku-ku, Tokyo, Japan, its successors, assigns, and legal representatives, the full and exclusive right to said invention and said application and to any and all inventions described in said application for the United States, its territorial possessions and all foreign countries, and the entire right title and interest in and to any and all Letters Patent which may be granted therefor in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties;

Agree that Seiko Epson Corporation, hereinafter referred to as Assignee, may apply for and receive Letters Patent for said invention and said inventions, hereinafter referred to as said invention, in its own name, in the United States, its territorial possessions, and all foreign countries; and that, when requested to carry out in good faith the intent and purpose of this assignment, at the expense of said Assignee, its successors, assigns and legal representatives, the undersigned will execute all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, execute all rightful oaths, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to said Assignee, its successors, assigns or legal representatives all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or legal representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said invention and for vesting title to said invention and all applications for patents on said invention in said Assignee, its successors, assigns, or legal representatives; and

06-03-14;05:31PM;セイコーエプソン(株)7F市東 知財課本部

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そして、私/私達は、この書面により譲渡された権利や財産に影響する、如何なる譲渡、長権、抵当権、ライセンス等その他の協定も他の第三者との間で行っていないこと；下記に署名した私/私達によって、この書面に記載されている権利が所有されていることを、当該譲受人、後継者、被譲渡者、及び法定代理人に対して誓約するものである。

さらに、下記に署名した私/私達はこの譲渡書は英語の部分の表現によってのみ解釈されることに同意する。

上記を証明するため、私/私達は下記日付で署名する。

Covenant with said Assignee, its successors, assigns, or legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

I/WE, the undersigned do further agree that this Assignment is to be construed solely according to the terms of the English language portions thereof.

IN TESTIMONY WHEREOF I/WE have hereunto set MY/OUR signature seal on the date indicated below.

唯一または第一発明者名 島田 浩行		Full name of sole or first inventor Hiroyuki SHIMADA	
発明者の署名 島田 浩行	日付 2006年3月10日	Inventor's signature Hiroyuki Shimada	Date March 10, 2006
第二共同発明者 (いる場合)		Full name of second joint inventor, if any	
第二共同発明者の署名	日付	Second inventor's signature	Date
第三共同発明者 (いる場合)		Full name of third joint inventor, if any	
第三共同発明者の署名	日付	Third inventor's signature	Date
第四共同発明者 (いる場合)		Full name of fourth joint inventor, if any	
第四共同発明者の署名	日付	Fourth inventor's signature	Date
第五共同発明者 (いる場合)		Full name of fifth joint inventor, if any	
第五共同発明者の署名	日付	Fifth inventor's signature	Date
第六共同発明者 (いる場合)		Full name of sixth joint inventor, if any	
第六共同発明者の署名	日付	Sixth inventor's signature	Date
第七共同発明者 (いる場合)		Full name of seventh joint inventor, if any	
第七共同発明者の署名	日付	Seventh inventor's signature	Date
第八共同発明者 (いる場合)		Full name of eighth joint inventor, if any	
第八共同発明者の署名	日付	Eighth inventor's signature	Date